

# INTERNATIONAL STANDARD

# IEC 61249-2-13

First edition  
1999-02

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## Materials for printed boards and other interconnecting structures –

### Part 2-13: Sectional specification set for reinforced base materials, clad and unclad – Cyanate ester non-woven aramid laminate of defined flammability, copper-clad

*Matériaux pour circuits imprimés et autres structures  
d'interconnexion –*

*Partie 2-13:  
Collection de spécifications intermédiaires pour les matériaux  
de base renforcés, recouverts ou non de feuille conductrice –  
Stratifié à base d'aramide non tissé collé avec de la résine  
cyanate ester, recouvert de cuivre, d'inflammabilité définie*

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Commission Electrotechnique Internationale  
International Electrotechnical Commission  
Международная Электротехническая Комиссия

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## CONTENTS

	Page
FOREWORD .....	3
Clause	
1 Scope .....	4
2 Normative references .....	4
3 Materials and construction.....	4
4 Internal marking .....	4
5 Electrical properties .....	5
6 Non-electrical properties of the copper-clad laminate .....	5
7 Non-electrical properties of the base material after complete removal of the copper foil .....	10
8 Packaging and marking .....	12
9 Acceptance testing.....	12
Annex A (informative) Conversion table for test method reference numbers .....	13

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**MATERIALS FOR PRINTED BOARDS AND OTHER  
INTERCONNECTING STRUCTURES –**

**Part 2-13: Sectional specification set for reinforced base materials,  
clad and unclad –**

**Cyanate ester non-woven aramid laminate of defined flammability,  
copper-clad**

FOREWORD

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International Standard IEC 61249-2-13 has been prepared by IEC technical committee 52: Printed circuits.

The text of this standard is based on the following documents:

FDIS	Report on voting
52/791/FDIS	52/802/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

Annex A is for information only.

A bilingual version of this standard may be issued at a later date.

## **MATERIALS FOR PRINTED BOARDS AND OTHER INTERCONNECTING STRUCTURES –**

### **Part 2-13: Sectional specification set for reinforced base materials, clad and unclad –**

#### **Cyanate ester non-woven aramid laminate of defined flammability, copper-clad**

## **1 Scope**

This part of IEC 61249 gives requirements for properties of cyanate ester non-woven aramid copper-clad laminate of defined flammability, in thicknesses of 0,05 mm up to 6,4 mm.

NOTE – To designate this material, the reference: 61249-2-13 – FV1 0– IEC – CE – AP – Cu may be used; if there is no risk of confusion, the type designation may be abbreviated to read IEC-61249-2-13-FV1.

## **2 Normative references**

The following normative documents contain provisions which, through reference in this text, constitute provisions of this part of IEC 61249-2. At the time of publication, the editions indicated were valid. All normative documents are subject to revision, and parties to agreements based on this part of IEC 61249-2 are encouraged to investigate the possibility of applying the most recent editions of the normative documents listed below. Members of IEC and ISO maintain registers of currently valid International standards.

IEC 61189-2:1997, *Test methods for electrical materials, interconnection structures and assemblies – Part 2: Test methods for materials for interconnection structures*

IEC 61249-5-1:1995, *Materials for printed boards and interconnecting structures – Part 5: Sectional specification set for conductive foils and films with or without coatings – Section 1: Copper foils (for the manufacture of copper-clad base materials)*